

☒ Original ☐ Supplemental ☐ Substitute ☐ PCT ☐ Design

TITLE: SEMICONDUCTOR DEVICE, SEMICONDUCTOR PACKAGE FOR USE THEREIN,
AND MANUFACTURING METHOD THEREOF

and as amended on _____ (if applicable).

I hereby claim foreign priority benefits under Title 35, United States Code, §119 (and §172 if this application is for a Design) of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

COUNTRY	APPLICATION NO.	DATE OF FILING	PRIORITY CLAIMED
Japan	H09-190818	July 16, 1997	YES

Page 1 of 3

Full Name of 4th Inventor	FAMILY NAME	FIRST GIVEN NAME	SECOND GIVEN NAME
Residence & Citizenship	CITY	STATE OR COUNTRY	COUNTRY OF CITIZENSHIP
Post Office Address	ADDRESS	CITY	STATE OR COUNTRY ZIP CODE

Full Name of 5th Inventor	FAMILY NAME	FIRST GIVEN NAME	SECOND GIVEN NAME
Residence & Citizenship	CITY	STATE OR COUNTRY	COUNTRY OF CITIZENSHIP
Post Office Address	ADDRESS	CITY	STATE OR COUNTRY ZIP CODE

1st Inventor Takaaki Sasaki Date 4.8.3.19
Takaaki SASAKI

2nd Inventor _____ Date _____

3rd Inventor _____ Date _____

4th Inventor _____ Date _____

5th Inventor _____ Date _____

Atty Docket No.: _____